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April 2015

FDMC2523P P-Channel QFET[®]

-150V, -3A, 1.5Ω

Features

- Max $r_{DS(on)} = 1.5\Omega$ at $V_{GS} = -10V$, $I_D = -1.5A$
- Low Crss (typical 10pF)
- Fast Switching
- Low gate charge (typical 6.2 nC)
- Improved dv / dt capability
- RoHS Compliant

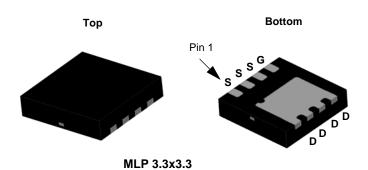


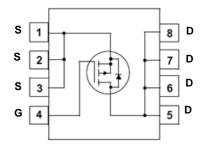
General Description

These P-Channel MOSFET enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.

Application

■ Active Clamp Switch





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{DS}	Drain to Source Voltage	-150	V
V_{GS}	Gate to Source Voltage	±30	V
	Drain Current -Continuous $T_C = 25^{\circ}C$	-3	
I _D	-Continuous $T_C = 100^{\circ}C$	-1.8	Α
	-Pulsed	-12	
P_{D}	Power Dissipation (Steady State) T _C = 25°C	42	W
E _{AS}	Single Pulse Avalanche Energy (Note 5)	3.3	mJ
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C
dv/dt	Peak Diode Recovery dv/dt (Note 2)	-5	V/ns

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	3.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	60	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
2523P	FDMC2523P	MLP 3.3x3.3	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-138		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -150V, V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			-1 -10	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-3	-3.8	-5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		6		mV/°C
_	Static Drain to Source On Resistance	$V_{GS} = -10V, I_D = -1.5A$		1.1	1.5	Ω
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -10V$, $I_D = -1.5A$, $T_J = 125$ °C		2.0	3.6	
9 _{FS}	Forward Transconductance	$V_{DS} = -40V, I_{D} = -1.5A$ (Note 4)		1.4		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -25V, V _{GS} = 0V, f = 1MHz		200	270	pF
C _{oss}	Output Capacitance			60	80	pF
C _{rss}	Reverse Transfer Capacitance			10	15	pF
R_g	Gate Resistance	f = 1MHz	0.1	7.5	15	Ω

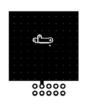
Switching Characteristics

	•				
t _{d(on)}	Turn-On Delay Time	.,,	15	27	ns
t _r	Rise Time	$V_{DD} = -75V$, $I_{D} = -3A$ $V_{GS} = -10V$, $R_{GEN} = 25\Omega$	11	20	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -10V, R _{GEN} = 2512 (Note 3.4)	19	35	ns
t _f	Fall Time	(11010 0, 1)	13	24	ns
Q_g	Total Gate Charge	V _{GS} = -10V	6.2	9	nC
Q_{gs}	Gate to Source Gate Charge	V _{DD} = -75V	1.4		nC
Q_{gd}	Gate to Drain "Miller" Charge	I _D = -3A (Note 3,4)	3.3		nC

Drain-Source Diode Characteristics

Is	Maximum continuous Drain - Source Diode Forward Current				-3	Α
I _{SM}	Maximum Pulse Drain - Source Doide Forward Current				-12	Α
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_{S} = -3.0A$		-1.8	-5	V
t _{rr}	Reverse Recovery Time	$I_F = -3.0A$, di/dt = 100A/ μ s		93		ns
Q _{rr}	Reverse Recovery Charge	(No	ote 3)	0.27		μС

^{1:} R_{0JA} is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 60°C/W when mounted on a 1 in² pad of 2 oz copper



b.135°C/W when mounted on a minimum pad of 2 oz copper

- I_{SD} ≤ -3A, dI/dt ≤ 300A/us, V_{DD} ≤ B_{VDSS}, Starting T_J = 25°C
 Pulse Test: Pulse Width < 300µs, Duty cycle < 2.0%.
 Essentially independent of operating temperature.
 E_{AS} of 3.3 mJ is based on starting T_J = 25 °C; P-ch: L = 3 mH, I_{AS} = -1.5 A, V_{DD} = -150 V, V_{GS} = -10 V.

Typical Characteristics T_J = 25°C unless otherwise noted

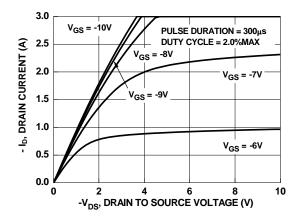


Figure 1. On-Region Characteristics

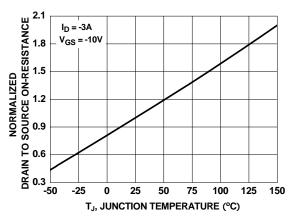


Figure 3. Normalized On-Resistance vs Junction Temperature

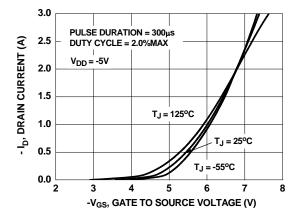


Figure 5. Transfer Characteristics

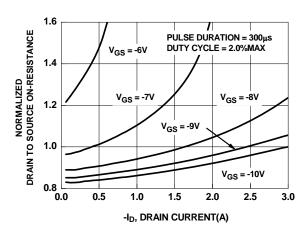


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

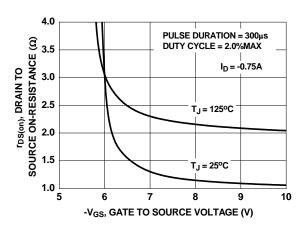


Figure 4. On-Resistance vs Gate to Source Voltage

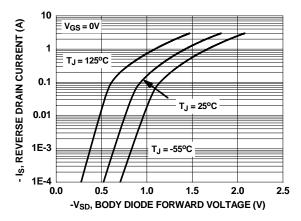


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

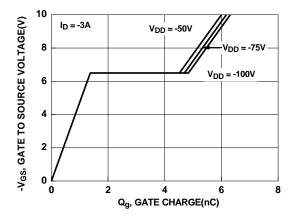


Figure 7. Gate Charge Characteristics

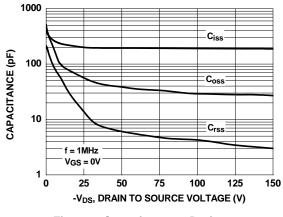


Figure 8. Capacitance vs Drain to Source Voltage

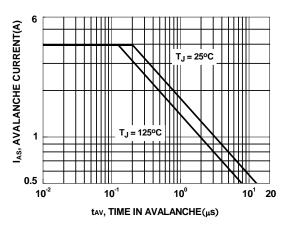


Figure 9. Unclamped Inductive Switching Capability

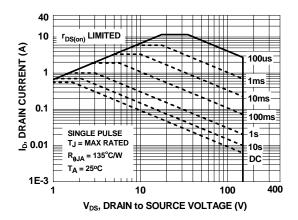


Figure 10. Forward Bias Safe Operating Area

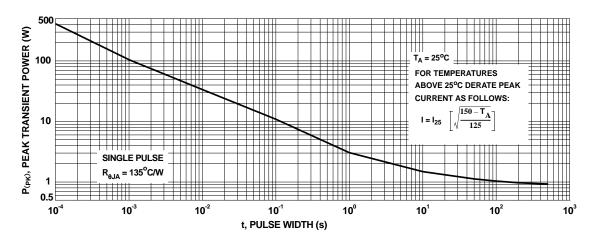


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

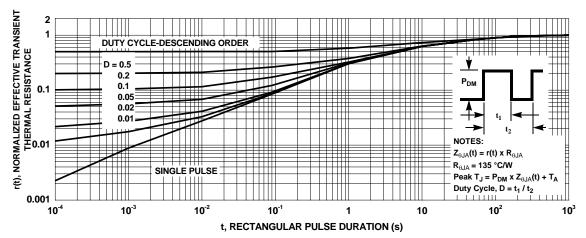
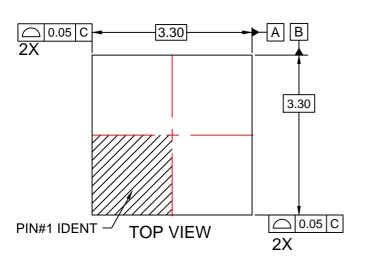
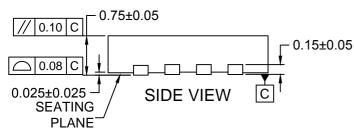
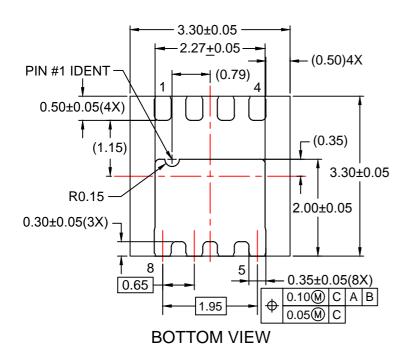
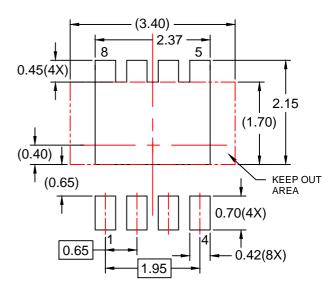


Figure 12. Transient Thermal Response Curve









RECOMMENDED LAND PATTERN

NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP08Srev3.



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